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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**  
(Case No. 207.010-US)

In the Application of: **LUTZ ET AL.**

) Group Art Unit: **2814**

Serial No: **10/698,258**

) Before

Filed: **OCTOBER 31, 2003**

) Examiner: **Le, Dung Anh**

Title: **ANTI-STICTION TECHNIQUE FOR THIN FILM  
AND WAFER-BONDED ENCAPSULATED  
MICROELECTROMECHANICAL SYSTEMS**

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**Certificate of Mailing under 37 CFR 1.8**

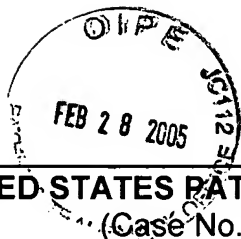
I hereby certify that the attached: **(1)** Amendment and Reply of February 23, 2005  
(12 pages) + Abstract of the Disclosure (1 page), and **(2)** Replacement Sheets of Drawings  
(8 sheets) are being deposited with the United States Postal Service with sufficient postage  
as first class mail in an envelope addressed to:

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on February 23, 2005.

  
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**AMENDMENT AND REPLY OF FEBRUARY 23, 2005**

Dear Sir:

Kindly amend the application as follows: